Date Created : 2007/05/07 Date Issued On : 2007/05/16

PCN# : **Q1070501-B**

DESIGN/PROCESS CHANGE NOTIFICATION -- FINAL

This is to inform you that a design and/or process change will be made to the following product(s). This notification is for your information and concurrence.

If you require data or samples to qualify this change, please contact **Fairchild Semiconductor** within 30 days of receipt of this notification.

Updated process quality documentation, such as FMEAs and Control Plans, are available for viewing upon request.

If you have any questions concerning this change, please contact:

Technical Contact:

Name: Ti, CS

E-mail: CS.Ti@fairchildsemi.com Phone: 604-6437211 ext 685

PCN Originator: Name: Ti, CS

E-mail: CS.Ti@fairchildsemi.com Phone: 604-6437211 ext 685

Implementation of change:

Expected 1st Device Shipment Date: 2007/06/25

Earliest Year/Work Week of Changed Product: H2

Change Type Description: Bond Wire Material Composition

Description of Change (From): Wire bond material currently used for our MLP 5x6 discrete products assembled from Fairchild (M), FSPM facility will be changed from Au wire to Cu wire. Package with this change will have an identifier. There will be no change in terms of wire diameter and type of thermosonic bonding process applied.

Description of Change (To): From Au wire used in MLP 5x6 Discrete products to Cu wire

Reason for Change: Change from Au wire to Cu wire a more robust wire bonding process. There will be no adverse impact on products' quality and reliability. Products will be assembled at the same quality level as before.

Qual/REL Plan Numbers: Q20060405

Qualification:

Qualification lots passed all reliability tests with zero failures

Results/Discussion

Test: (Autoclave)					
Lot	Device	96-HOURS	Failure Code		
Q20060405AAACLV	FDMS8690	0/79			
Q20060405ABACLV	FDMS8690	0/79			
Q20060405ACACLV	FDMS8690	0/79			
Q20060405ADACLV	FDMS8690	0/79			

Q20060405BAACLV		FDMS2572			0/79			
Test: (High Tempe	rature	Gate Rias)					I.	
Lot	Devi		168-HO	IIPS	500-HOURS	10	00-HOURS	Failure Code
Q20060405AAHTGB		MS8690	0/79	UNO	300-HOUKS	10	00-110013	i allule Code
Q20000403AATTOB	I DIV	100090	0/13		0/79			
					0/13	0/	79	
Q20060405ABHTGB			0/79			0,		
Q20000+05/\BITTOB			0/13		0/79			
					0/13	0/	79	
Q20060405ACHTGB			0/79			0,		
Q20000+00/(OITFOB			0/13		0/79			
					0,70	0/	79	
Q20060405ADHTGB			0/79					
42000010071211102			6,1.0		0/79			
					0,10	0/	79	
Q20060405BAHTGB	FDM	/IS2572	0/79			-	-	
4200001002711102			6,1.0		0/79			
					1	0/	79	
T . (111 L T	+	5 5:	<u> </u>		1		•	
Test: (High Tempe								
Lot	Devi		168-HO	URS	500-HOURS	10	00-HOURS	Failure Code
Q20060405AAHTRB	FDN	/IS8690	0/79					
					0/79			
						0/	79	
Q20060405ABHTRB			0/79					
					0/79			
						0/	79	
Q20060405ACHTRB			0/79					
					0/79			
						0/	79	
Q20060405ADHTRB			0/79					
					0/79			
						0/	79	
Q20060405BAHTRB	FDN	/IS2572	0/79					
					0/79			
						0/	79	
Test: (High Tempe	rature	Storage Life)						
Lot	Devi		168-HO	URS	500-HOURS	10	00-HOURS	Failure Code
Q20060405AAHTSL		1S8690	0/79					- andre dede
					0/79			
						0/	79	
Q20060405ABHTSL			0/79			-	-	
					0/79			
						0/	79	
Q20060405ACHTSL			0/79			-	-	
					0/79			
					1	0/	79	
Q20060405ADHTSL			0/79					
			5,.0		0/79	+		
					1	0/	79	
Q20060405BAHTSL	FDM	MS2572	0/79					
					0/79	+		
						0/	79	
T+- (D- 0 :	<u> </u>				<u> </u>	Γ'		I
Test: (Power Cycle	;)	1= .				1		<u></u>
Lot		Device		5000-C	YCLES	10000-	CYCLES	Failure Code
Q20060405AAPRCL		FDMS8690		0/79				
Q20060405AAPRCL		FDMS8690				0/79		
Q20060405ABPRCL		FDMS8690		0/79		0 /=:		
Q20060405ABPRCL		FDMS8690				0/79		
Q20060405ACPRCL		FDMS8690		0/79				
Q20060405ACPRCL		FDMS8690				0/79		
Q20060405ADPRCL		FDMS8690		0/79				
Q20060405ADPRCL		FDMS8690		1		0/79		
Q20060405BAPRCL		FDMS2572		0/79		ļ.,		
Q20060405BAPRCL		FDMS2572				0/79		
Test: -65C, 150C (Temp	erature Cvcle						
Lot		Device	•	100-CY	CLES	500-C	/CLES	Failure Code
		- 31100		100 01	J_LU	0000		

Q20060405AATMCL1	FDMS8690	0/79				
Q20060405AATMCL1	FDMS8690		0/79			
Q20060405ABTMCL1	FDMS8690	0/79				
Q20060405ABTMCL1	FDMS8690		0/79			
Q20060405ACTMCL1	FDMS8690	0/79				
Q20060405ACTMCL1	FDMS8690		0/79			
Q20060405ADTMCL1	FDMS8690	0/79				
Q20060405ADTMCL1	FDMS8690		0/79			
Q20060405BATMCL1	FDMS2572	0/79				
Q20060405BATMCL1	FDMS2572		0/79			
Test: 130C (Highly Acc	celerated Stress Test)				
Lot	Device	96-H0	DURS	Failure Code		
Q20060405AAHAST1	FDMS8690	0/79				
Q20060405ABHAST1	FDMS8690	0/79				
Q20060405ACHAST1	FDMS8690	0/79				
Q20060405ADHAST1	FDMS8690	0/79				
Q20060405BAHAST1	FDMS2572	0/79				
Test: MSL(1), PKG(Sm	nall), PeakTemp(260	c), Cycles(3) (Pred	condition)			
Lot	Device	Resul	ts	Failure Code	ailure Code	
Q20060405AAPCNL1A	FDMS8690	0/237				
Q20060405ABPCNL1A	FDMS8690	0/237				
Q20060405ACPCNL1A	FDMS8690	0/237				
Q20060405ADPCNL1A	FDMS8690	0/237				
Q20060405BAPCNL1A	FDMS2572	0/237				

Product Id Description :

Affected FSIDs:

FDMS2572	FDMS3572	FDMS3672
FDMS8690		